ECTC Panel: Advancements in Bio-Medical Technology & Associated Packaging

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Imagination at work.

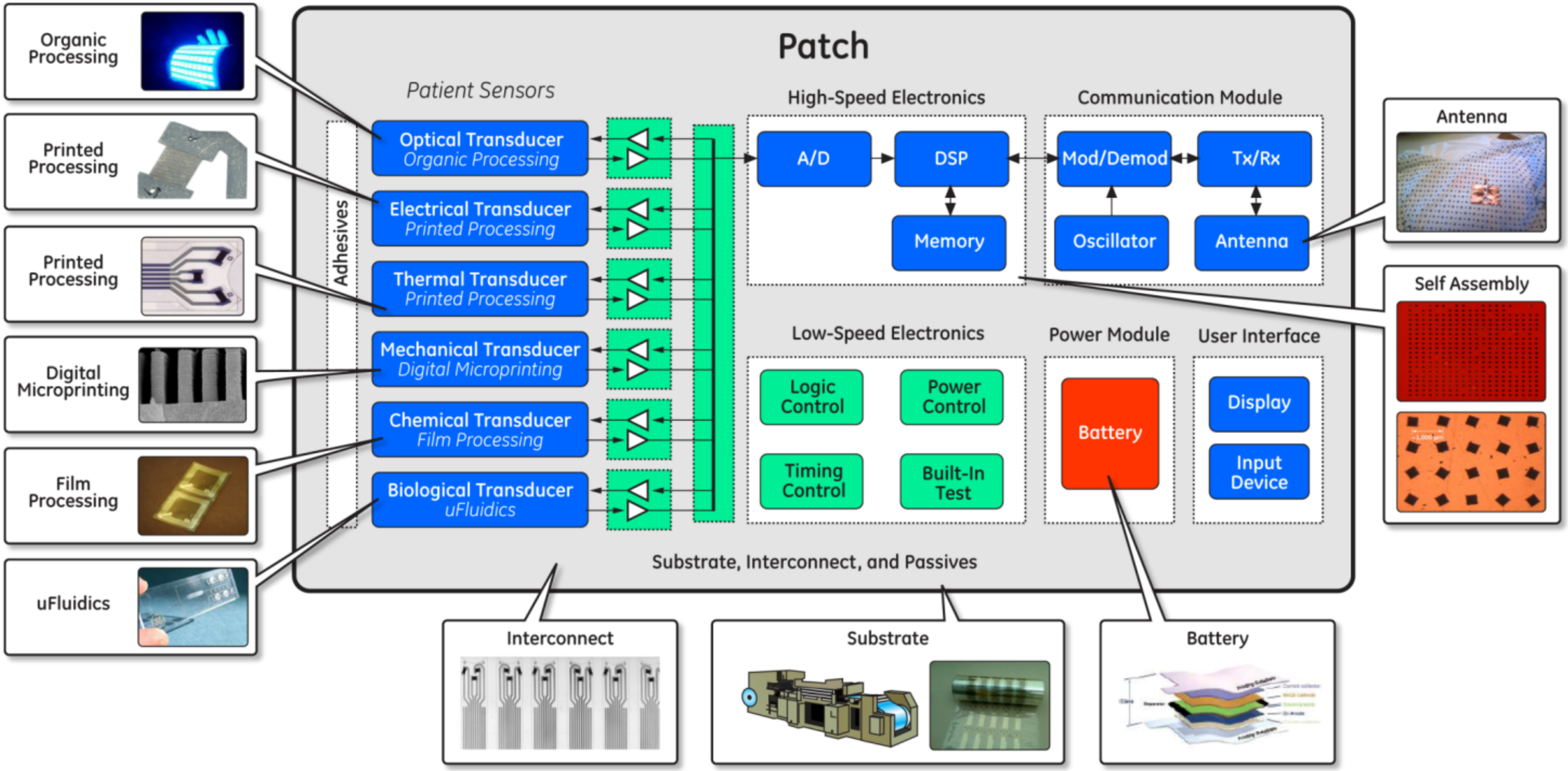
GE Products, Systems, Technology

PRODUCTS

SYSTEMS & COMPONENTS

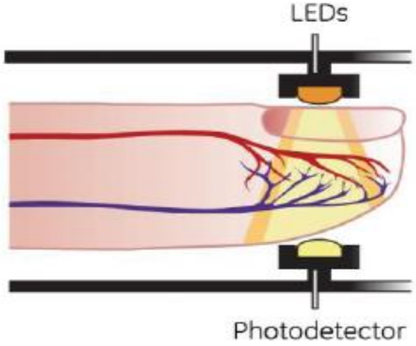
PACKAGING TECHNOLOGY

Next Generation Wearable Electronics Technologies

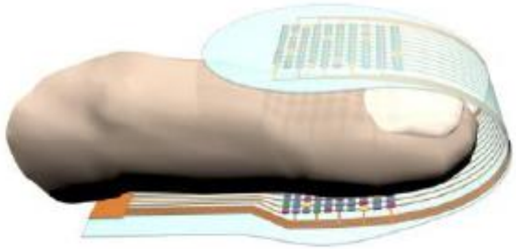


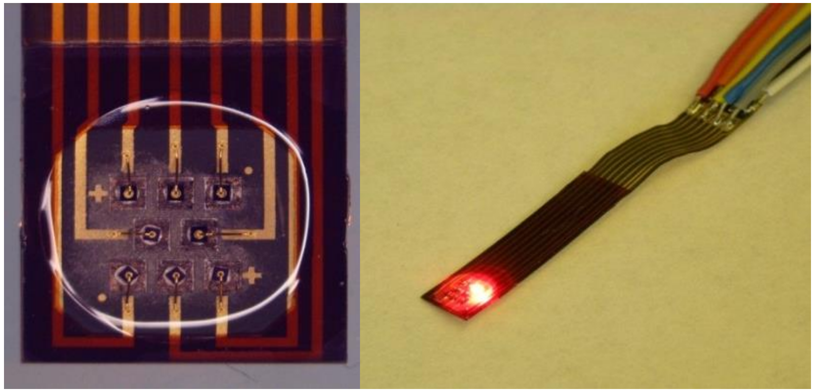
Multi-wavelength Photoplethysmograph Sensor

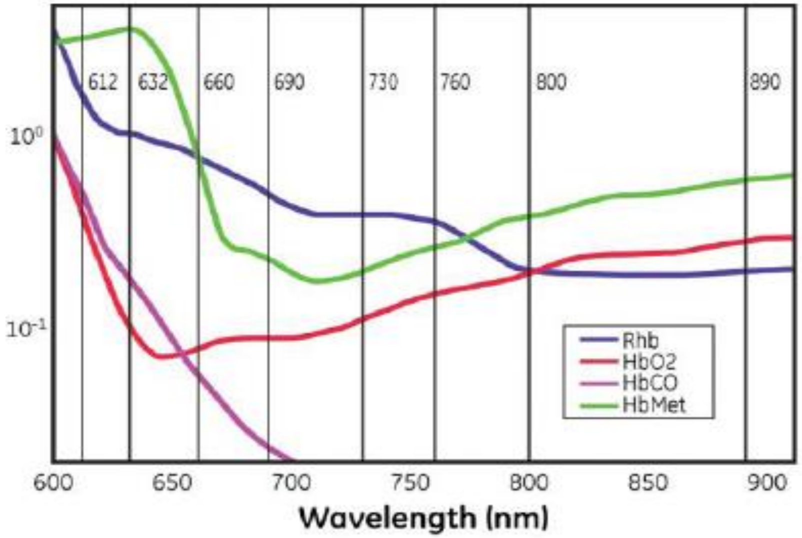
Two LEDs



Multiple LEDs

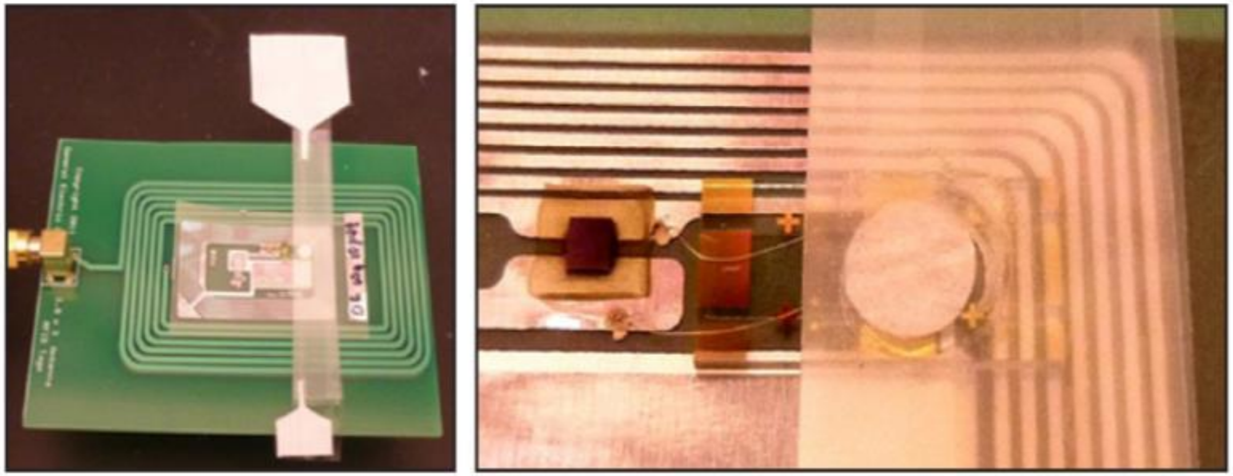


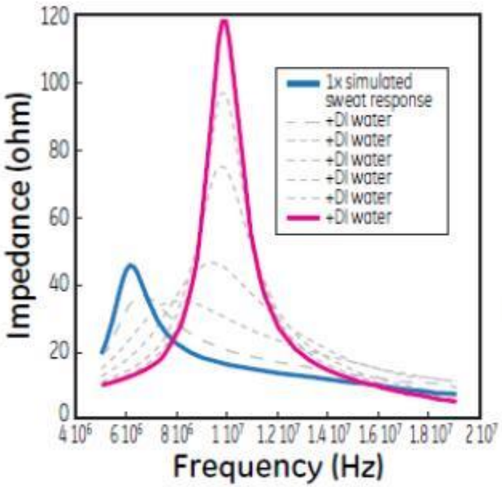


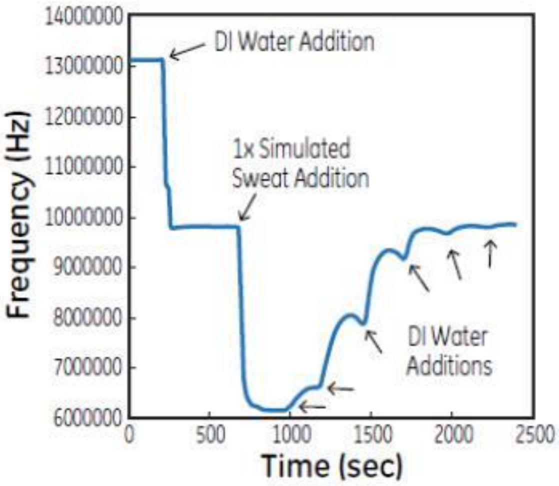


Measurement of all hemoglobin fractions in blood

Wearable Impedance RF Sweat Sensors

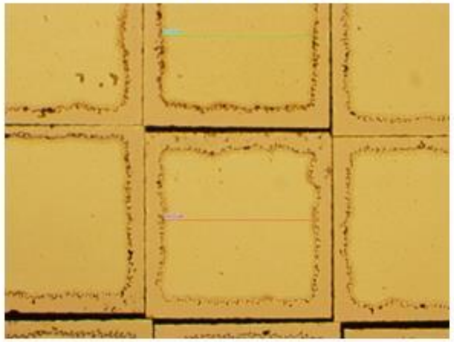




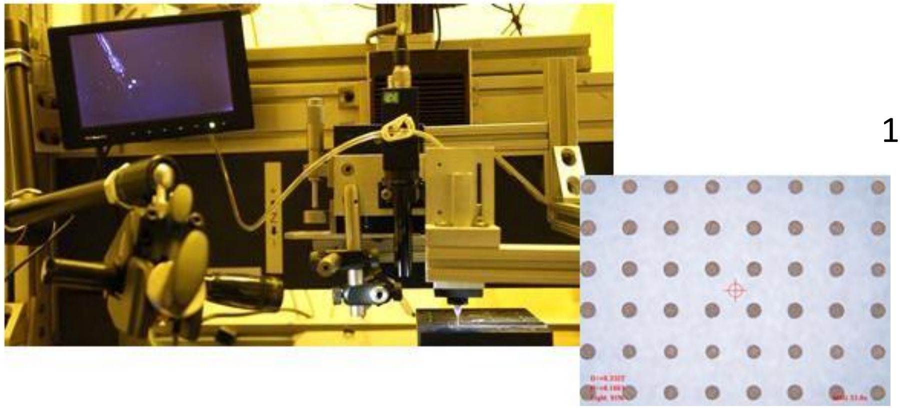


Magnetically Directed Assembly

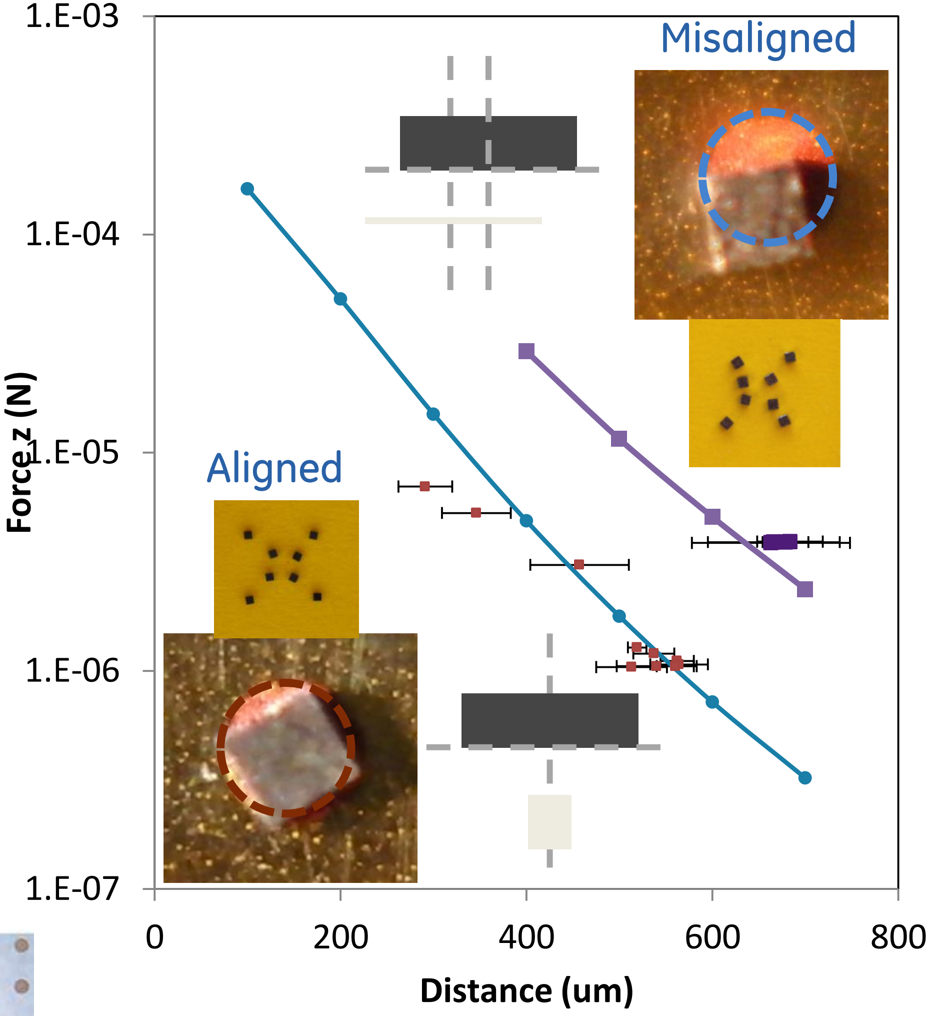
Bulk Electroplating of ***Soft*** Magnets onto Chips at Wafer Fab



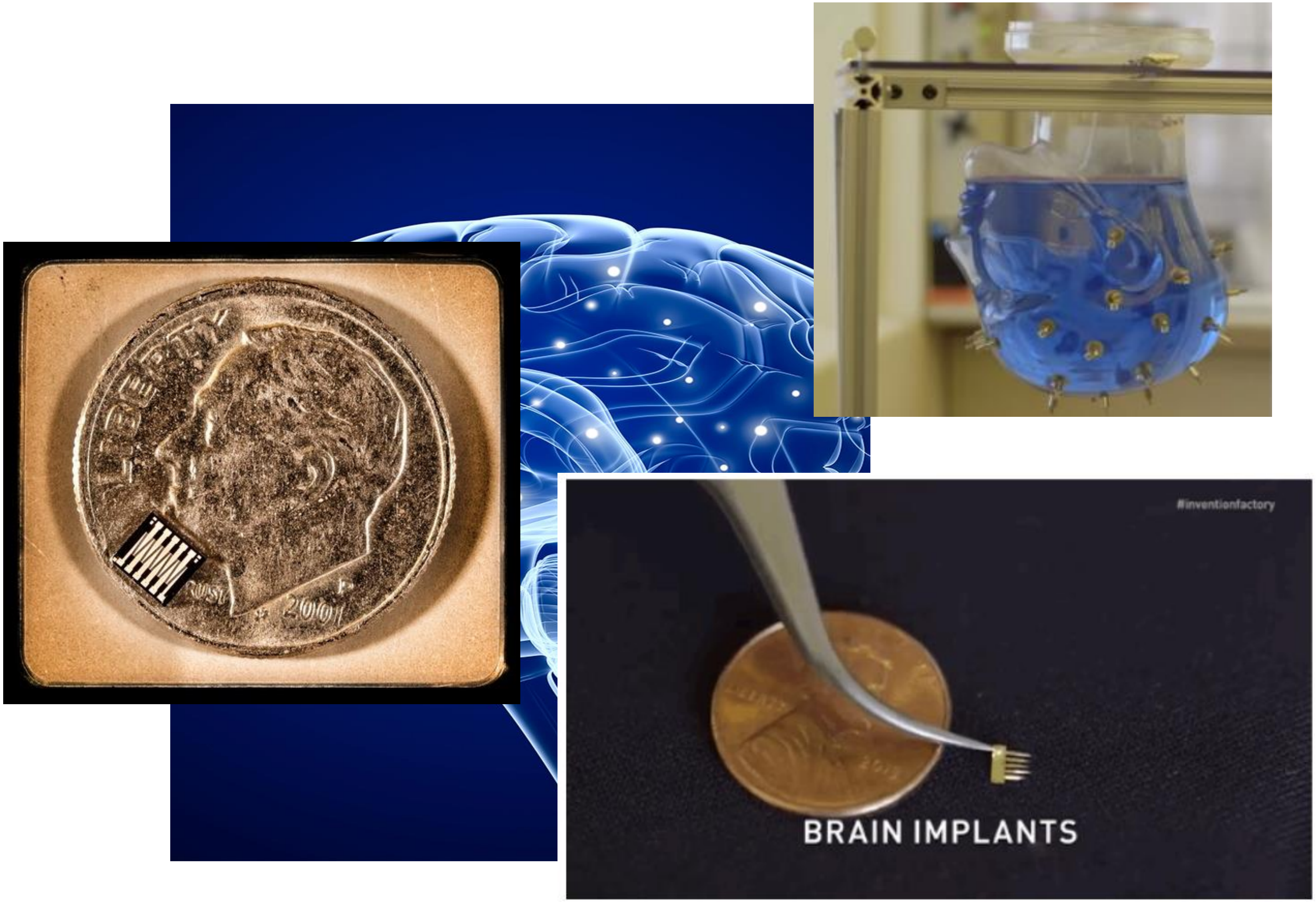
Direct Printing of ***Hard*** Magnets on Reusable Templates



3D Force Simulations



Current and Future Interests: Brain



A prototype of a GE brain probe. Image credit: GE Global Research